



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



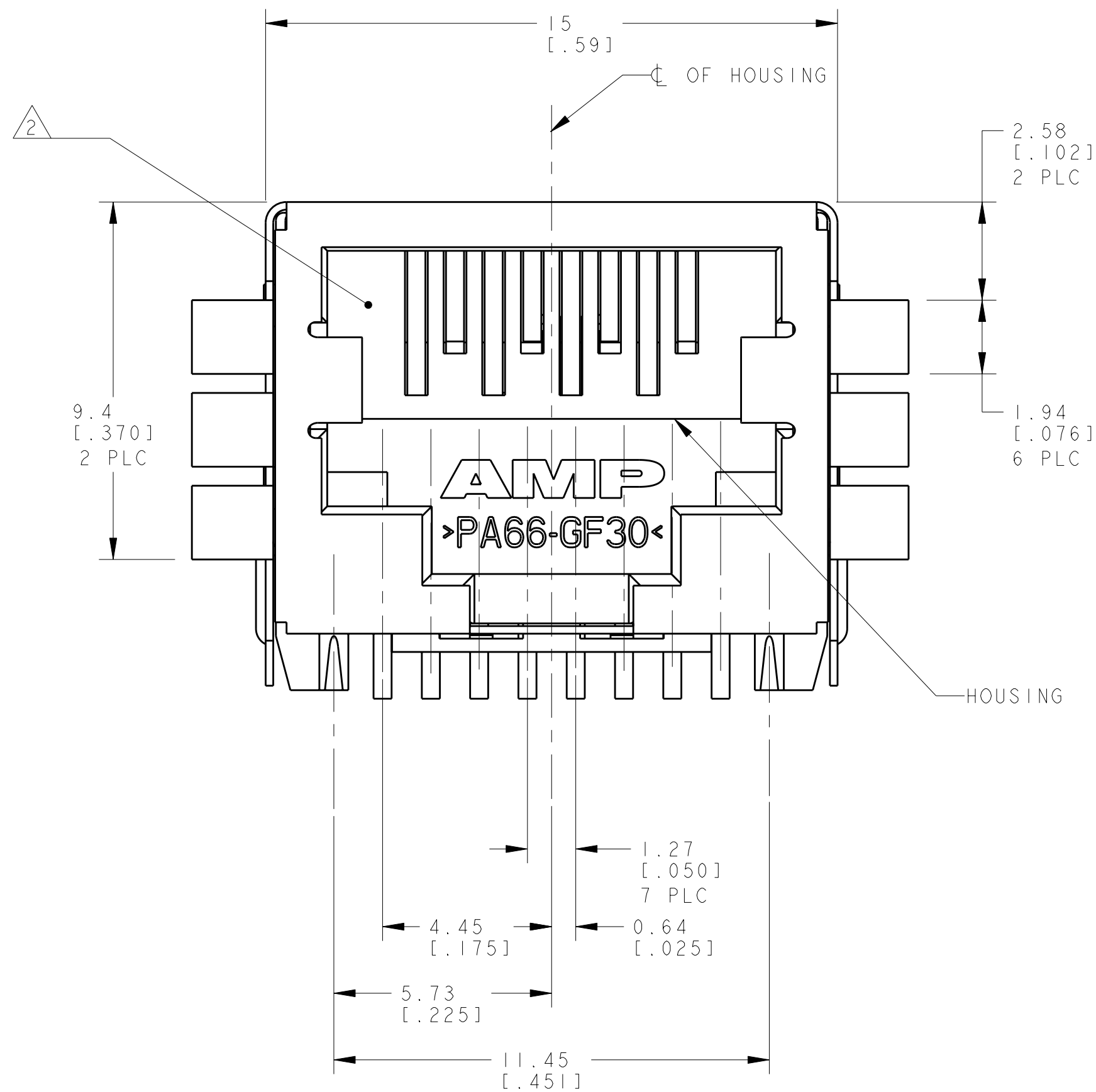
## Contact us

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△ MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-0,  
IR REFLOW SOLDERING PROCESS COMPATIBLE.  
TERMINALS - 0.25[.010] THICK PHOSPHOR BRONZE PLATED WITH  
3.8[μm(.000150)] MINIMUM THICK BRIGHT TIN-LEAD IN SOLDER  
AREA, 1.27[μm(.000050)] MINIMUM GOLD IN LOCALIZED PLATE AREA.  
ENTIRE TERMINAL PLATED WITH 1.27[μm(.000050)] MINIMUM THICK  
NICKEL.  
SHIELD - 0.1[.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH  
2.0-4.0[μm(.000079-.000157)] THICK TIN OVER 1.27[μm(.000050)] MIN THICK NICKEL

 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68,  
SUBPART F.

3 THIS DIMENSION REPRESENTS THE TOTAL HEIGHT OF THE CONNECTOR FROM THE TOP OF THE PC BOARD.

THIS DIMENSION HAS A MAXIMUM VALUE OF 20.50[.807] WHEN JACK IS INSTALLED BEHIND PANEL.

5. PACKAGED 66 ASSEMBLIES PER PVC TRAY, 396 PER BOX.

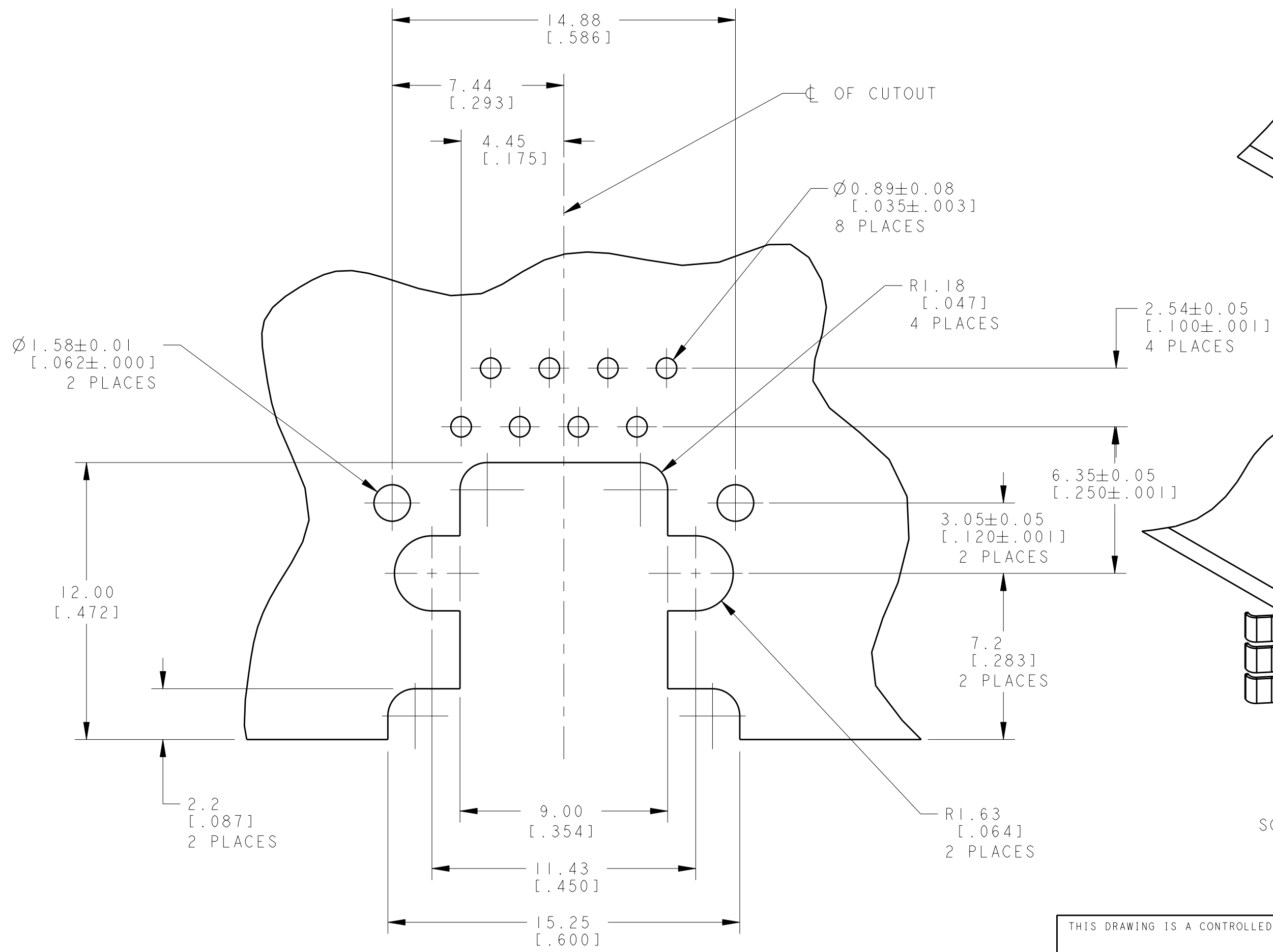
MANUFACTURING DATE CODE:  
ORIENTED AND LOCATED APPROXIMATELY AS SHOWN. BLACK INK STAMP.  
TEXT HEIGHT APPROXIMATELY 2MM.

FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR  
NEXT 2 DIGITS = MANUFACTURING WORK WEEK  
LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1

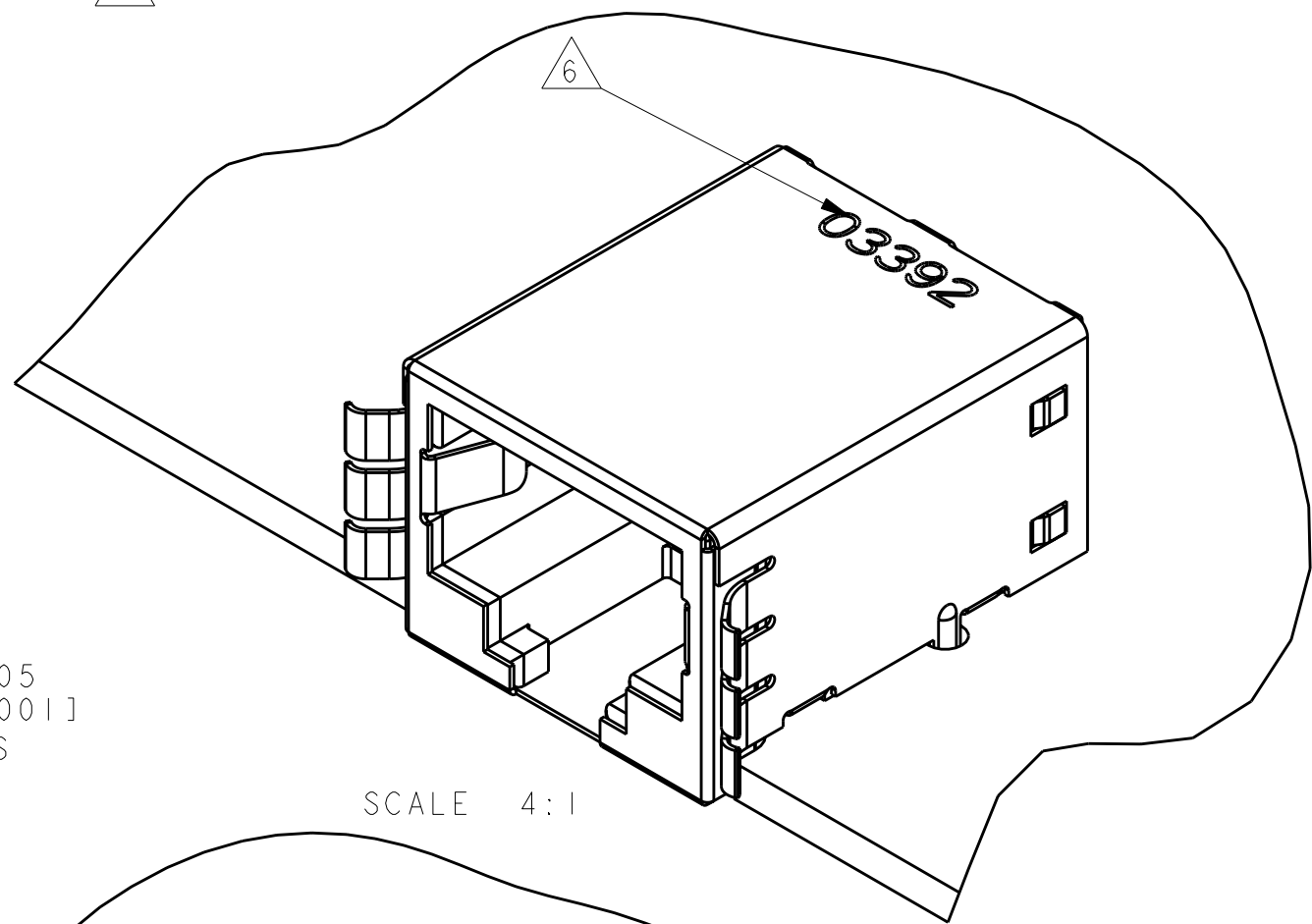
△ MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, BLACK, UL 94V-O,  
IR REFLOW SOLDERING PROCESS COMPATIBLE.  
TERMINALS - 0.25[.010] THICK PHOSPHOR BRONZE PLATED WITH  
3.8[μm(.000150)] MINIMUM THICK MATTE TIN IN SOLDER  
AREA, 1.27[μm(.000050)] MINIMUM GOLD IN LOCALIZED PLATE AREA.  
ENTIRE TERMINAL PLATED WITH 1.27[μm(.000050)] MINIMUM THICK  
NICKEL.  
SHIELD - 0.1[.0039] MIN THICK COPPER ZIN ALLOY, PREPLATED WITH  
2.0-4.0[μm(.000079-.000157)] THICK TIN OVER 1.27[μm(.000050)] MIN THICK NICKEL

8 PACKED WITH TAPE AND REEL PACKAGE.

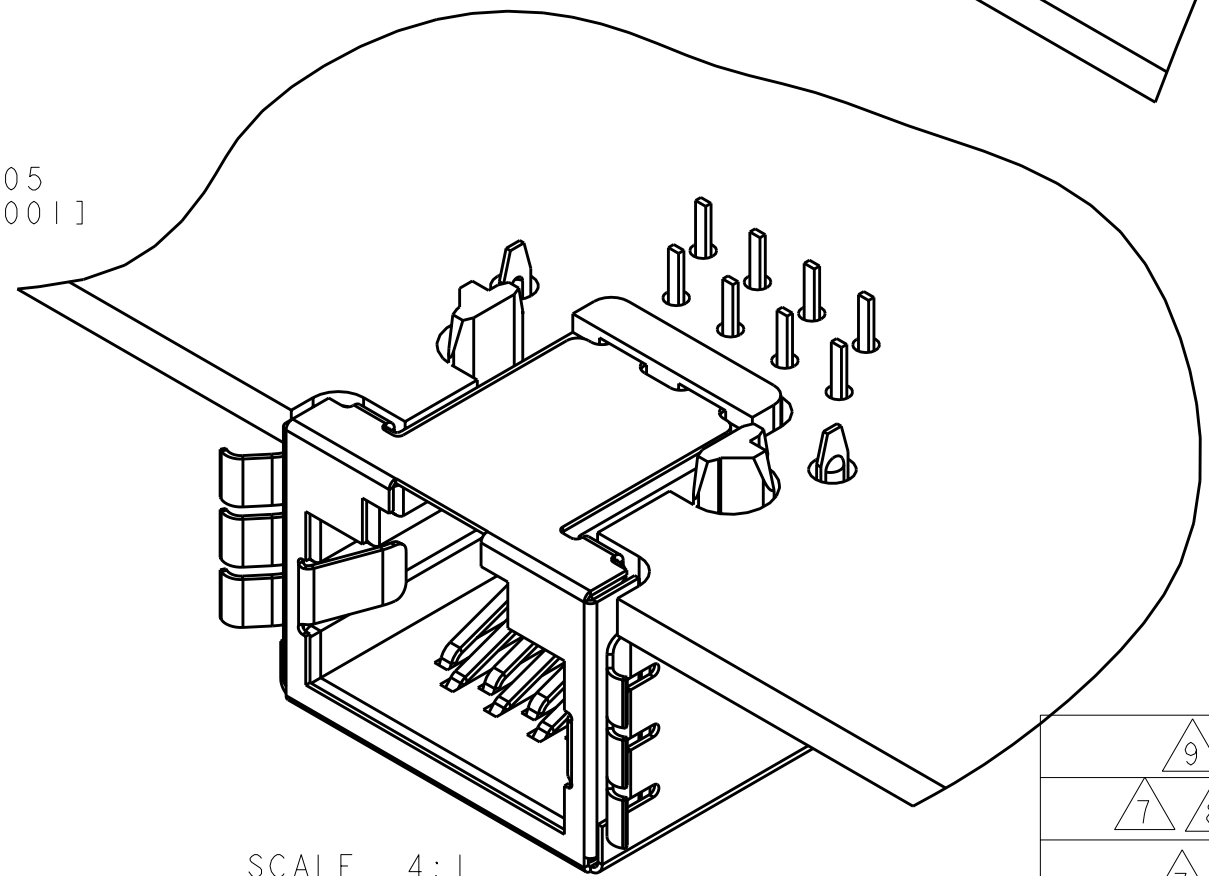
9 MATERIAL: SHIELD - 0.1[.0039] MIN THICK COPPER ZINC ALLOY, PREPLATED WITH 1.27 $\mu$ m (.000050) MIN THICK NICKEL, PCB GROUND TABS DIPPED WITH 2.03 $\mu$ m (.000080) MIN TIN.  
OTHER COMPONENT: AS SAME AS 7








SUGGESTED PRINTED CIRCUIT  
BOARD LAYOUT  
COMPONENT SIDE  
SCALE 6:1





SCALE 4:1



SCALE 4:1

	1116062-4
 	1116062-3
	1116062-2
	1116062-1
MATERIAL/ FINISH	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN 11NOV98 CHK D. KEMPA DATE 11NOV98		 TE Connectivity	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME MODULAR JACK ASSEMBLY, 8 POSITION, SHIELDED, 10mm	
		0 PLC ± 2 PLC ±0.13(0.005) 3 PLC ± 4 PLC ± ANGLES ±		PRODUCT SPEC 108-1163 APPLICATION SPEC 114-2048	
MATERIAL SEE P/N TABLE		FINISH SEE P/N TABLE		SIZE CAGE CODE DRAWING NO 3.49 grams A100779C1116062	
				RESTRICTED TO -	
				CUSTOMER DRAWING SCALE 8:1 SHEET 1 OF 1 REV P	